BROADCOM®

Data Sheet

HLMP-331x, HLMP-341x, HLMP-351x Series

T-1¾ (5 mm) High Intensity LED Lamps

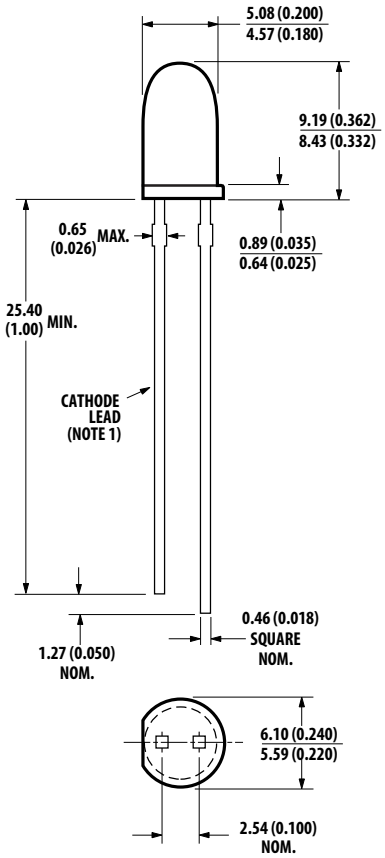
Overview

This Broadcom® family of T-1¾ nondiffused LED lamps is specially designed for applications requiring higher on-axis intensity than is achievable with a standard lamp. The light generated is focused to a narrow beam to achieve this effect.

Features

- High intensity
- AlInGaP LED technology
- Choice of three bright colors:
  - Red
  - Yellow
  - Green
- Popular T-1¾ diameter package
- Selected minimum intensities
- Narrow viewing angle
- General-purpose leads
- Reliable and rugged
- Available on tape and reel

Package Dimensions



NOTE:

1. All dimensions are in mm (inches).
2. An epoxy meniscus may extend about 1 mm (0.040 in.) down the leads.
3. For PCB hole recommendations, see Precautions.

Device Selection Guide

Color	Part Number	Luminous Intensity I_V (mcd) at 10 mA	
		Min.	Max.
Red	HLMP-3316	24.8	—
	HLMP-3316-I00xx	24.8	—
Yellow	HLMP-3416	16.6	—
Green	HLMP-3519	12.0	—
	HLMP-3519-F00xx	12.0	—

Absolute Maximum Ratings at T_A = 25°C

Parameter	Red/Orange	Yellow	Green	Units
Peak Forward Current	90	60	90	mA
Average Forward Current[a]	25	20	25	mA
DC Current[b]	30	20	30	mA
Power Dissipation[c]	135	85	135	mW
Reverse Voltage (I_R = 100 µA)	5	5	5	V
LED Junction Temperature	110	110	110	°C
Operating Temperature Range	–40 to +100	–40 to +100	–20 to +100	°C
Storage Temperature Range	–40 to +100	–40 to +100	–40 to +100	°C

a. See Figure 4 (Red), Figure 8 (Yellow), or Figure 12 (Green) to establish pulsed operating conditions.

b. For Red and Green series, derate linearly from 50°C at 0.5 mA/°C. For Yellow series, derate linearly from 50°C at 0.2 mA/°C.

c. For Red and Green series, derate power linearly from 25°C at 1.8 mW/°C. For Yellow series, derate power linearly from 50°C at 1.6 mW/°C.

Electrical/Optical Characteristics at T_A = 25°C

Parameter	Symbol	Device	Min.	Typ.	Max.	Units	Test Conditions
Luminous Intensity	I_V	3316	24.8	60.0	—	mcd	I_F = 10 mA
		3416	16.6	50.0	—		
		3519	12.0	70.0	—		
Included Angle Between Half Luminous Intensity Points	$2\theta_{1/2}$	3316	—	35	—	Deg.	I_F = 10 mA, See Note [a]
		3416	—	35	—		
		3519	—	24	—		
Peak Wavelength	λ_{PEAK}	331X	—	632	—	nm	Measurement at Peak
		341X	—	590	—		
		351X	—	570	—		
Dominant Wavelength	λ_d	331X	—	626	—	nm	See Note [b]
		341X	—	589	—		
		351X	—	569	—		
Spectral Line Halfwidth	$\Delta\lambda_{1/2}$	331X	—	14	—	nm	
		341X	—	12	—		
		351X	—	13	—		
Speed of Response	τ_s	331X	—	90	—	ns	
		341X	—	90	—		
		351X	—	500	—		
Capacitance	C	331X	—	11	—	pF	V_F = 0; f = 1 MHz
		341X	—	15	—		
		351X	—	18	—		
Thermal Resistance	$R\theta_{J\text{-}PIN}$	331X	—	260	—	°C/W	Junction to Cathode Lead
		341X	—	260	—		
		351X	—	260	—		
Forward Voltage	V_F	331X	—	1.9	2.4	V	I_F = 10 mA
		341X	—	1.9	2.4		
		351X	—	2.0	2.7		
Reverse Breakdown Voltage	V_R	All	5.0	—	—	V	I_R = 100 µA
Luminous Efficacy	η_V	331X	—	180	—	lumens/watt	See Note [c]
		341X	—	500	—		
		351X	—	640	—		

a. $\theta_{1/2}$ is the off-axis angle at which the luminous intensity is half the axial luminous intensity.

b. The dominant wavelength, λ_d, is derived from the CIE chromaticity diagram and represents the single wavelength that defines the color of the device.

c. Radiant intensity, I_e, in watts/steradian, may be found from the equation $I_e = I_v/\eta_v$, where I_v is the luminous intensity in candelas and η_v is the luminous efficacy in lumens/watt.

Part Numbering System

H L M P - | x_1 | x_2 | x_3 | x_4 | - | x_5 | x_6 | x_7 | x_8 | x_9 |

Code	Description	Option	
x_1	Package Type	3	T-1 $^3/_4$ (5 mm)
x_2	Color	3	Red
		4	Yellow
		5	Green
x_3 x_4	Brightness Level	16	Higher brightness
		19	
x_5	Minimum Intensity Bin	See Table 1, Intensity Bin Limits.	
x_6	Maximum Intensity Bin	0	Open bins (no max I_V bin limit)
x_7	Color Bin Option	0	Full distribution
x_8 x_9	Packaging Option	00	Bulk (Loose forms packaging)
		01	Tape and Reel, Crimped Leads
		02	Tape and Reel, Straight Leads
		B1	Right Angle Housing, Uneven Leads
		B2	Right Angle Housing, Even Leads

Bin Information

Table 1: Intensity Bin Limits

Color	Bin	Intensity Range (mcd)	
		Min.	Max.
Red	H	15.5	24.8
	I	24.8	39.6
	J	39.6	63.4
	K	63.4	101.5
	L	101.5	162.4
	M	162.4	234.6
	N	234.6	340.0
	O	340.0	540.0
	P	540.0	850.0
	Q	850.0	1200.0
	R	1200.0	1700.0
	S	1700.0	2400.0
	T	2400.0	3400.0
	U	3400.0	4900.0
	V	4900.0	7100.0
	W	7100.0	10200.0
	X	10200.0	14800.0
	Y	14800.0	21400.0
	Z	21400.0	30900.0
Yellow	G	16.6	26.5
	H	26.5	42.3
	I	42.3	67.7
	J	67.7	108.2
	K	108.2	173.2
	L	173.2	250.0
	M	250.0	360.0
	N	360.0	510.0
	O	510.0	800.0
	P	800.0	1250.0
	Q	1250.0	1800.0
	R	1800.0	2900.0
	S	2900.0	4700.0
	T	4700.0	7200.0
	U	7200.0	11700.0
	V	11700.0	18000.0
	W	18000.0	27000.0

Table 1: Intensity Bin Limits (Continued)

Color	Bin	Intensity Range (mcd)	
		Min.	Max.
Green	E	7.6	12.0
	F	12.0	19.1
	G	19.1	30.7
	H	30.7	49.1
	I	49.1	78.5
	J	78.5	125.7
	K	125.7	201.1
	L	201.1	289.0
	M	289.0	417.0
	N	417.0	680.0
	O	680.0	1100.0
	P	1100.0	1800.0
	Q	1800.0	2700.0
	R	2700.0	4300.0
	S	4300.0	6800.0
	T	6800.0	10800.0
	U	10800.0	16000.0
	V	16000.0	25000.0
	W	25000.0	40000.0

Maximum tolerance for each bin limit is ±18%.

Color Categories

Color	Category #	Lambda (nm)	
		Min.	Max.
Green	6	561.5	564.5
	5	564.5	567.5
	4	567.5	570.5
	3	570.5	573.5
	2	573.5	576.5
Yellow	1	582.0	584.5
	3	584.5	587.0
	2	587.0	589.5
	4	589.5	592.0
	5	592.0	593.0

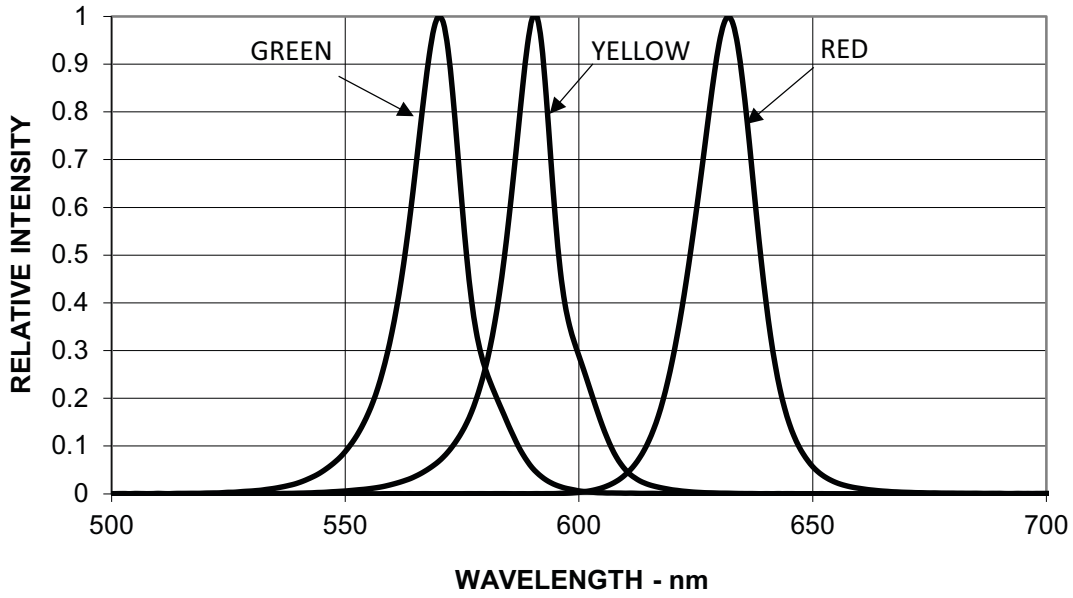
Tolerance for each bin limit is ±0.5 nm.

Packaging Option Matrix

Packaging Option Code	Definition
00	Bulk Packaging, minimum increment, 500 pieces/bag
01	Tape and Reel, crimped leads, minimum increment, 1300 pieces/reel
02	Tape and Reel, straight leads, minimum increment, 1300 pieces/reel
B1	Right-Angle Housing, uneven leads, minimum increment, 500 pieces/bag
B2	Right-Angle Housing, even leads, minimum increment, 500 pieces/bag

NOTE: All categories are established for classification of products. Products might not be available in all categories. Contact your local Broadcom representative for further clarification or information.

Figure 1: Relative Intensity vs. Wavelength



Red HLMP-331X Series

Figure 2: Forward Current vs. Forward Voltage

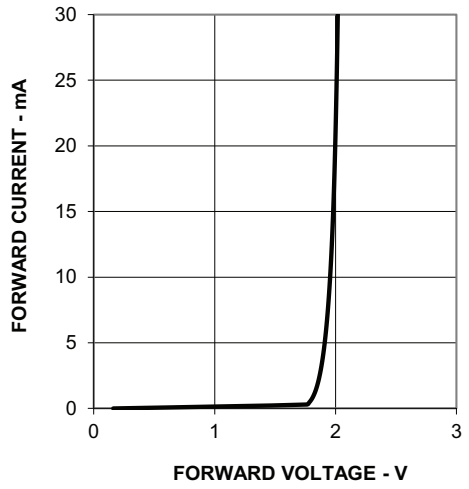


Figure 3: Relative Luminous Intensity vs. DC Forward Current

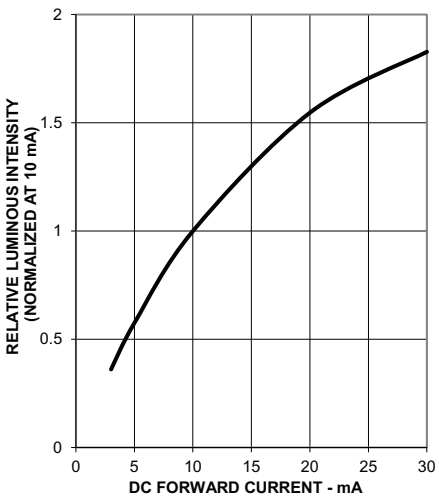


Figure 4: Maximum Tolerable Peak Current vs. Pulse Duration (IDC MAX as per MAX Ratings)

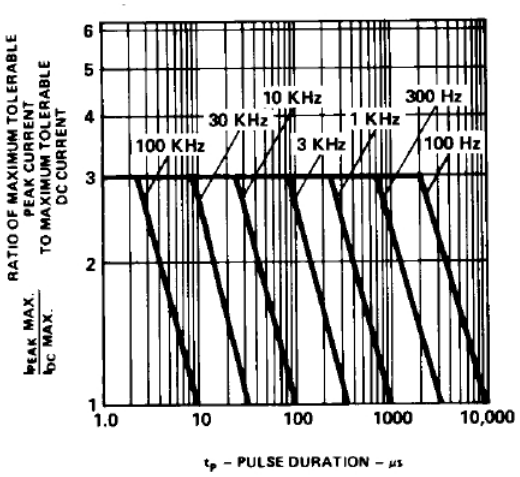
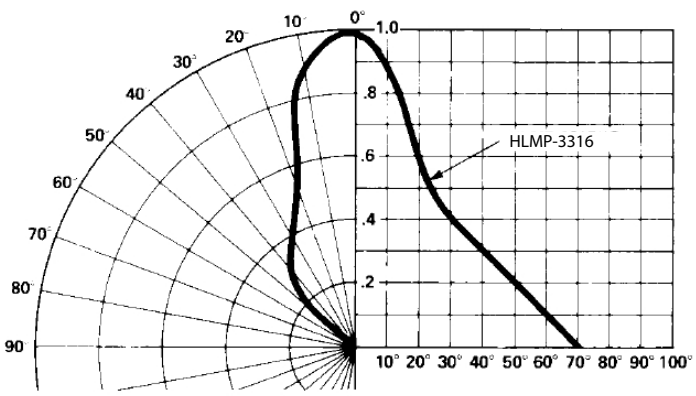


Figure 5: Relative Luminous Intensity vs. Angular Displacement



Yellow HLMP-341X Series

Figure 6: Forward Current vs. Forward Voltage

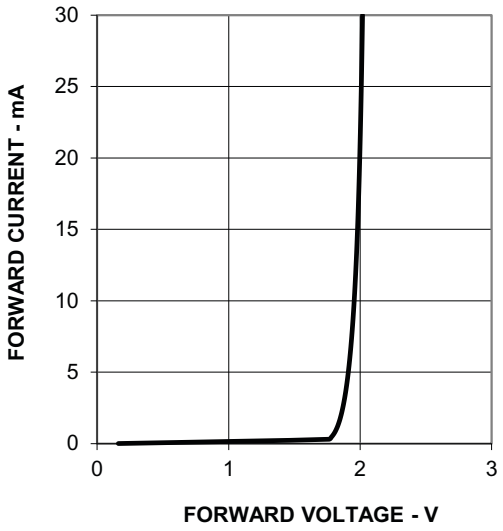


Figure 7: Relative Luminous Intensity vs. DC Forward Current

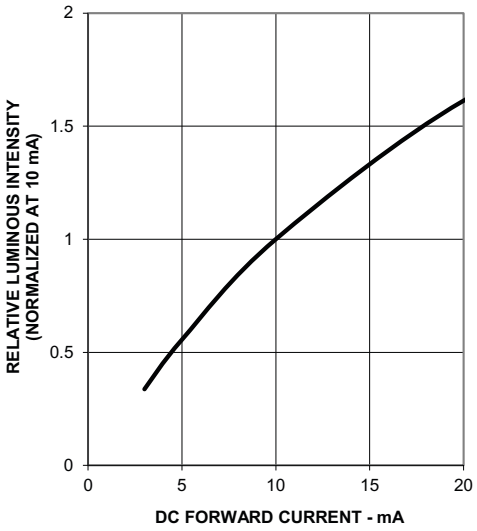


Figure 8: Maximum Tolerable Peak Current vs. Pulse Duration (IDC MAX as per MAX Ratings)

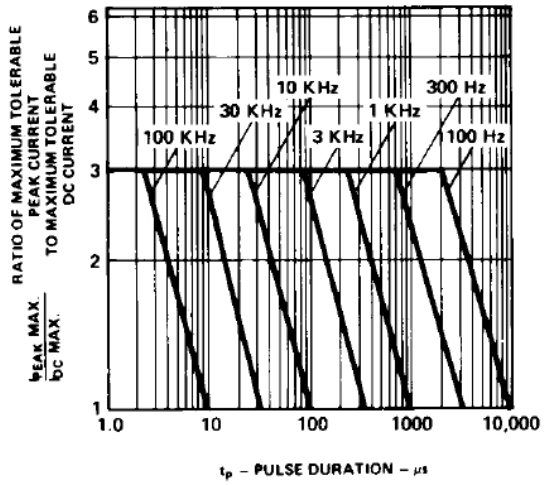
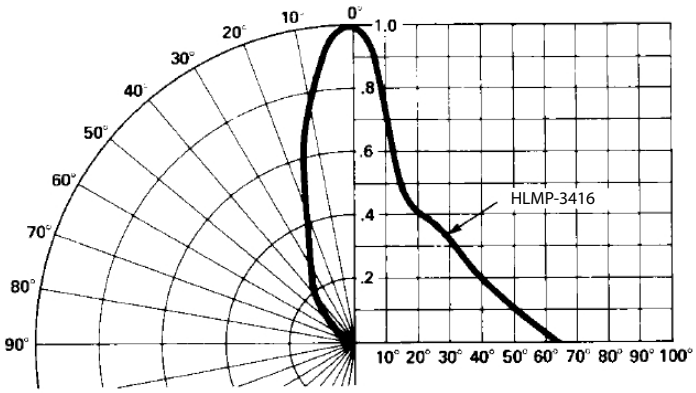


Figure 9: Relative Luminous Intensity vs. Angular Displacement



Green HLMP-351X Series

Figure 10: Forward Current vs. Forward Voltage

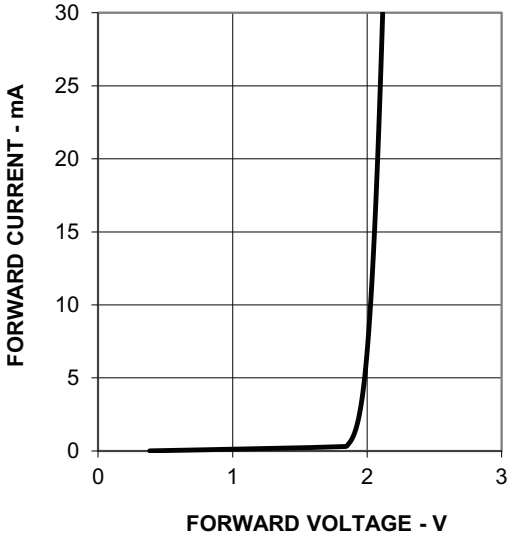


Figure 11: Relative Luminous Intensity vs. DC Forward Current

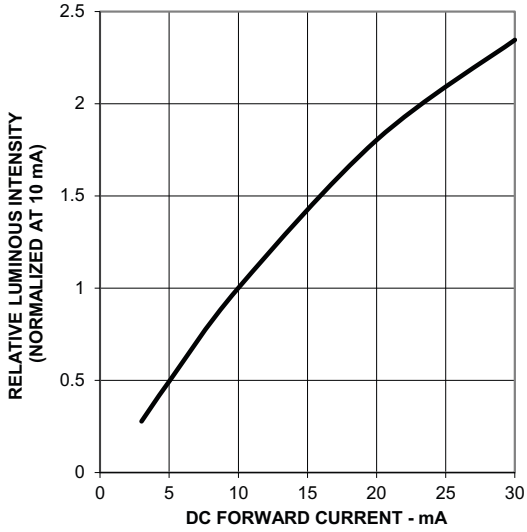


Figure 12: Maximum Tolerable Peak Current vs. Pulse Duration (IDC MAX as per MAX Ratings)

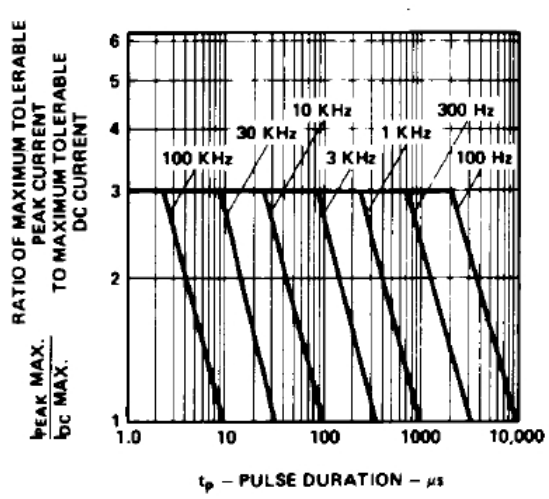
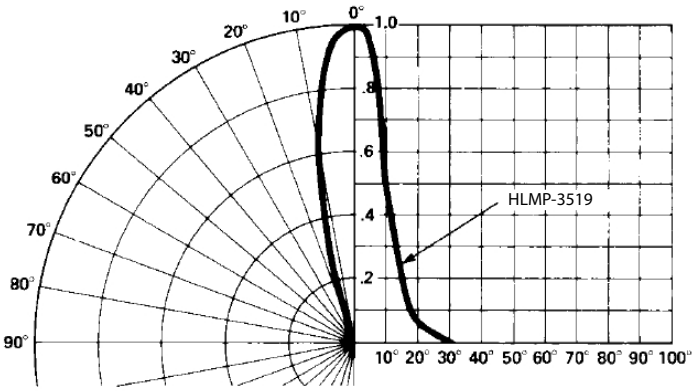


Figure 13: Relative Luminous Intensity vs. Angular Displacement



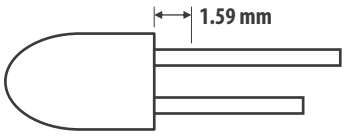
Precautions

Lead Forming

- The leads of an LED lamp may be preformed or cut to length prior to insertion and soldering on PC board.
- For better control, use the proper tool to precisely form and cut the leads to applicable length rather than doing it manually.
- If manual lead cutting is necessary, cut the leads after the soldering process. The solder connection forms a mechanical ground that prevents mechanical stress due to lead cutting from traveling into the LED package. Use this method for the hand soldering operation, because the excess lead length also acts as small heat sink.

Soldering and Handling

- Take care during the PCB assembly and soldering process to prevent damage to the LED component.
- The LED component may be effectively hand soldered to the PCB. However, do this under unavoidable circumstances, such as rework. The closest manual soldering distance of the soldering heat source (soldering iron's tip) to the body is 1.59 mm. Soldering the LED using soldering iron tip closer than 1.59 mm might damage the LED.



- Apply ESD precautions on the soldering station and personnel to prevent ESD damage to the LED component that is ESD sensitive. Refer to Broadcom application note AN 1142 for details. The soldering iron used must have a grounded tip to ensure electrostatic charge is properly grounded.
- Recommended soldering conditions:

	Wave Soldering[a, b]	Manual Solder Dipping
Pre-heat Temperature	105°C max.	—
Pre-heat Time	30s max.	—
Peak Temperature	250°C max.	260°C max.
Dwell Time	3s max.	5s max.

a. The preceding conditions refer to measurement with a thermocouple mounted at the bottom of the PCB.

b. Use only bottom pre-heaters to reduce thermal stress experienced by LED.

- Set and maintain wave soldering parameters according to the recommended temperature and dwell time. Perform daily checks on the soldering profile to ensure that it always conforms to the recommended soldering conditions.

NOTE:

1. PCBs with different size and design (component density) will have a different heat mass (heat capacity). This might cause a change in temperature experienced by the board if the same wave soldering setting is used. Therefore, recalibrate the soldering profile again before loading a new type of PCB.
2. Take extra precautions during wave soldering to ensure that the maximum wave temperature does not exceed 250°C and the solder contact time does not exceed 3s. Overstressing the LED during the soldering process might cause premature failure to the LED due to delamination.

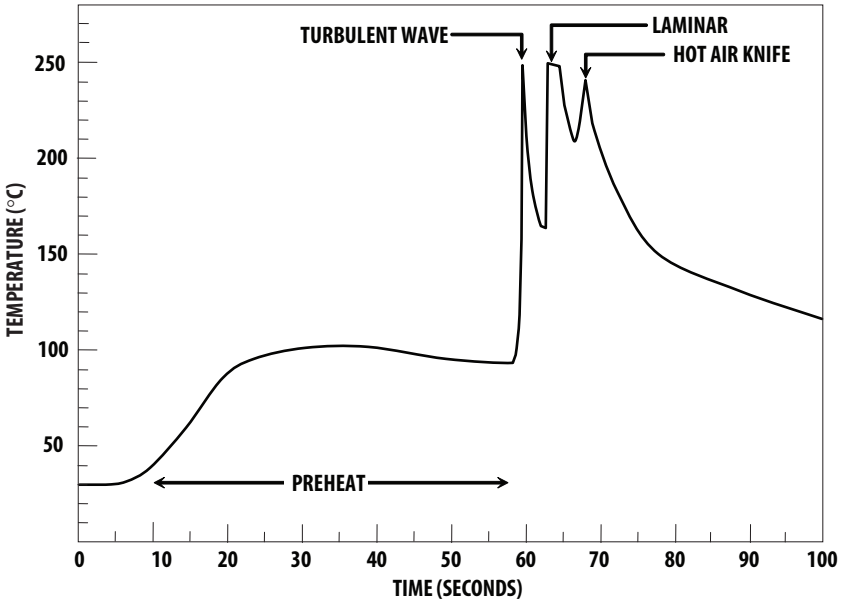
- Loosely fit any alignment fixture that is being applied during wave soldering and do not apply weight or force on the LED. Use non-metal material because it will absorb less heat during the wave soldering process.
- At elevated temperature, the LED is more susceptible to mechanical stress. Therefore, allow the PCB to cool down to room temperature prior to handling, which includes removal of alignment fixture or pallet.
- If the PCB board contains both through-hole (TH) LED and other surface-mount components, solder surface-mount components on the top side of the PCB. If the surface mount must be on the bottom side, solder these components using reflow soldering prior to the insertion of the TH LED.
- The recommended PC board plated through holes (PTH) size for LED component leads follows:

	LED Component Lead Size	Diagonal	Plated Through-Hole Diameter
Lead size (typ.)	0.45 × 0.45 mm (0.018 × 0.018 in.)	0.636 mm (0.025 in.)	0.98 to 1.08 mm (0.039 to 0.043 in.)
Dambar shear-off area (max.)	0.65 mm (0.026 in.)	0.919 mm (0.036 in.)	
Lead size (typ.)	0.50 × 0.50 mm (0.020 × 0.020 in.)	0.707 mm (0.028 in.)	1.05 to 1.15 mm (0.041 to 0.045 in.)
Dambar shear-off area (max.)	0.70 mm (0.028 in.)	0.99 mm (0.039 in.)	

- Oversizing the PTH can lead to a twisted LED after clinching. On the other hand, undersizing the PTH can cause difficulty inserting the TH LED.

Refer to application note AN1027 for more information about soldering and handling of TH LED lamps.

Figure 14: Recommended Wave Soldering Profile



Recommended solder:
Sn63 (Leaded solder alloy)
SAC305 (Lead-free solder alloy)

Flux: Rosin flux

Solder bath temperature:
245°C ± 5 °C (maximum peak temperature = 250°C)

Dwell time: 1.5s – 3.0s (maximum = 3 seconds)

Note: Allow for board to be sufficiently cooled to room temperature before you exert mechanical force.

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